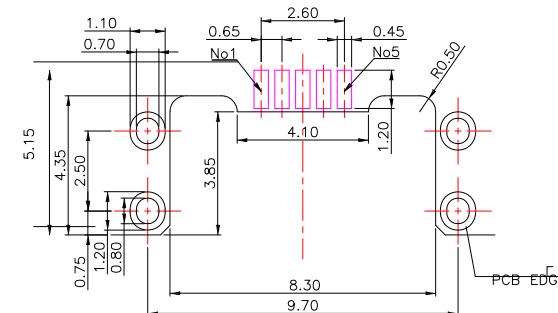
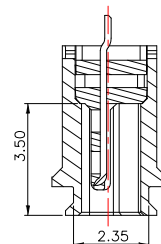
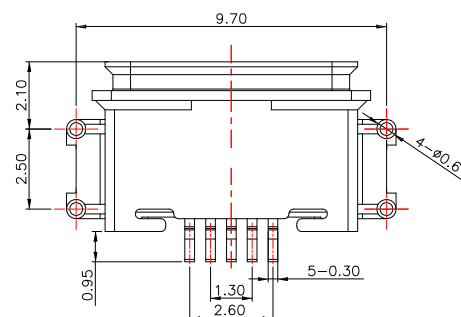




P.C.B LAYOUT MOUNTING PATTERN



MRUSB-5B-WP11-x-S382

— 鍍層厚度：

Blank : 1u"
2 : 15u"
3 : 30u"

NOTES:

MATERIAL:

- 1.1 HOUSING: HIGH-TEMP
1.2 CONTACT: COPPER ALLOY
1.3 SHELL: SUS

FINISH:

- 2.1 CONTACT: PLATED GOLD IN MATING AREA ;
GOLD PLATED ON SOLDER BALLS ;
NICKEL UNDER PLATED OVERALL
- 2.2 SHELL: NICKEL UNDER PLATED SURFACE LAYER
- 3.SPECIFICATION:
- 3.1 RATING: 1.8A(PIN1&5) , 0.5A(PIN2&3&4)
- 3.2 DIELECTRIC WITHSSTANDING VOLTAGE: 100 VAC
- 3.3 CONTACT RESISTANCE: 30 mΩ MAX.
- 3.4 INSULATION RESISTANCE: 1000 MΩ MIN.

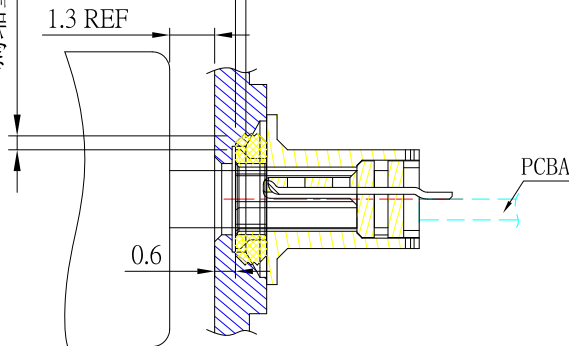
					 東莞市高迪電子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD	DRAWN BY: Jack Lu		DATE: 04/22/20	MAT'L		TITLE	CONNECTOR	
4	更新圖面	Jack	042220			CHECKED BY: Jacky Chen	DATE: 04/22/20	FINISH		MODLE	MICRO USB 5PF B TYPE 沉板 板上		
3	更新圖面	Jack	061118										
2	更新圖面	Jack	051418					SCALE	1 : 1	DWG NO.	MRUSB-5B-WP11-x-S382	SIZE A4	
1	更新為A0版	Jack	041018					APPROVED BY: Tony Kao	DATE: 04/22/20	SHEET NO.	1 of 2	VER R4	
ITEM NO.		DESCRIPTION		DRAWN	DATE	TOLERANCE UNLESS OTHERWISE STATED : Up to 5 ±0.2 Above 5 ~ 15 ±0.3 Above 15 ~ 30 ±0.4 Above 30 ~ 50 ±0.5 Angle ±0.3°		3RD. ANGEL'S		UNITS	MM		
A		B			C	D		E	F	G	H	I	J

IPX7

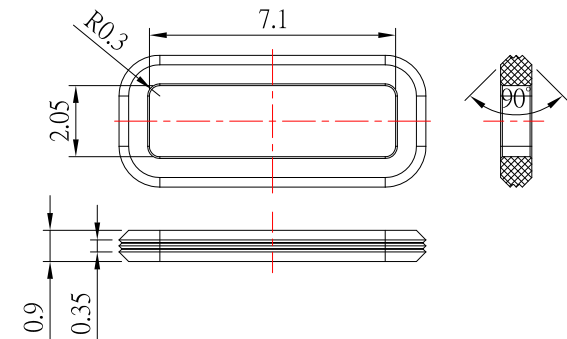


機殼面板對密封圈為縮量0.40Min
為縮量0.40Min

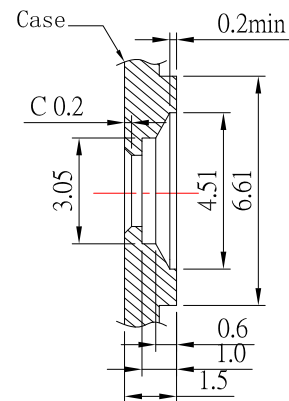
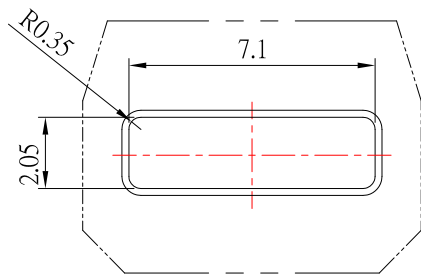
機殼面板對密封圈為縮量0.30Min
(建議壓縮量為密封圈直徑大小40-50%)



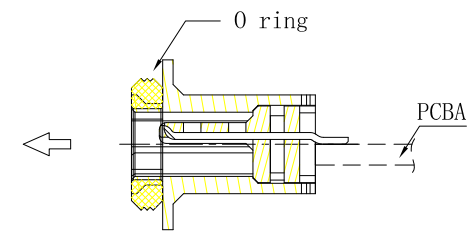
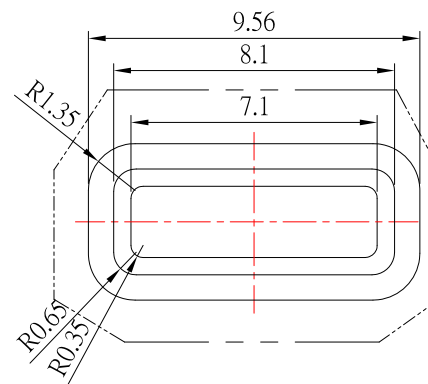
COMPRESSION RATIO TO BE 40%-50%



O RING design guide (SILICON RUBBER)



RECOMMENDED OPEN DIMENSION OF CASE



Assembly direction

東莞市高迪電子有限公司
DONG GUAN GAO DI ELECTRONICS CO., LTD

TOLERANCE UNLESS OTHERWISE STATED:
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD.
ANGEL'S



UNITS

MM

DRAWN BY:	DATE	MAT'L	TITLE	CONNECTOR
Jack Lu	04/22/20	FINISH	MODLE	MICRO USB 5PF B TYPE 沉板 板上
CHECKED BY:	DATE	SCALE	DWG NO.	H 1.42 IPX7
Jacky Chen	04/22/20	1 : 1	MRUSB-5B-WP11-x-S382	SIZE A4
APPROVED BY:	DATE	SHEET NO.	PART NO.	VER R4
Tony Kao	04/22/20	2 of 2	MRUSB-5B-WP11-x-S382	